

## CLAIMS

What is claimed is:

1. A contactless sheet resistance measurement apparatus for measuring sheet resistance comprising:

5 means for illuminating the area of semiconductor structure with intensity modulated light;

means for detecting SPV signals inside and outside said illumination area optically coupled to said illuminating means; and

10 means for measurement of said SPV signals inside and outside the illumination area connected to said means for detecting SPV signals.

2. A contactless sheet resistance measurement apparatus for measuring the sheet resistance of claim 1, wherein said illumination means comprises a light emitting diode with a driver forming the sinusoidal illumination and an optical fiber directing the light onto the wafer surface.

15 3. A contactless sheet resistance measurement apparatus for measuring the sheet resistance of claim 1, wherein said means for detecting of SPV signals comprises a transparent conducting electrode optically coupled with a light source used for detecting SPV signal inside the illumination area and a non transparent electrode used for detecting SPV signal outside the illumination area.

20 4. A contactless sheet resistance measurement apparatus for measuring the sheet resistance of claim 3, wherein said transparent conducting electrode is a glass or quartz disk with ITO coating and the non transparent electrode is metal ring coaxially installed to said glass or quartz disk.

5. A contactless sheet resistance measurement apparatus for measuring the sheet resistance of claim 3, wherein said transparent and conducting electrode is a glass or quartz disk with an ITO coating and the non transparent electrode is a part of the metal ring coaxially installed to said glass disk.

6. A contactless sheet resistance measurement method, comprising the steps of:

illumination of the area of the semiconductor structure with known sheet resistance through a transparent electrode with intensity modulated light;

measurement of the SPV signal from the transparent electrode;

10 adjustment of the light flux to obtain linear dependence of the SPV signal versus light flux;

measurement of SPV signals  $V_{s0}$ ;

measurement of SPV signal  $V_{s1}$  at the same conditions for wafer with unknown  $Rs$ ; and

15 determination of the sheet resistance using measured  $RATIO = V_{s1}/V_{s0}$ , and the calculated curve or table  $RATIO(Rs)$ .

7. A contactless sheet resistance measurement method, comprising the steps of:

illumination the area of the semiconductor structure through a transparent electrode with intensity modulated light at maximum frequency corresponding to bandwidth of SPV preamplifier and lock-in amplifier;

measurement of the SPV signal,  $V_{s1}$ , from the transparent electrode;

20 adjustment of the light flux to get linear dependence of the SPV signal,  $V_{s1}$ , versus light flux;

measurement of SPV signals,  $V_{s1}$  and  $V_{s2}$ ;  
adjustment of light modulating frequency to get the ratio of SPV signals  $RATIO=V_{s1}/V_{s2}<5$  and measurement of  $V_{s1}$  and  $V_{s2}$  at this frequency; and  
determination of the sheet resistance using measured  $RATIO=V_{s1}/V_{s2}$ , and  
the calculated curve or table  $RATIO(R_s)$ .

5 8. A contactless method for measuring of sheet resistance and conductance of a p-n junction, comprising the steps of:

illumination the area of the semiconductor structure through a transparent electrode with intensity modulated light at maximum frequency,  $F$ , corresponding to a bandwidth of SPV preamplifier and lock-in amplifier;

10 measurement of the SPV signal,  $V_{s1}$ , from transparent electrode;

adjustment of the light flux to get linear dependence of the SPV signal,  $V_{s1}$ , versus light flux;

15 measurement of SPV signals and its phase shifts,  $V_{s1}, \theta_1$  and  $V_{s2}, \theta_2$  from transparent and non transparent electrodes;

decreasing of light modulating frequency to get the ratio of SPV signals  $RATIO=V_{s1}/V_{s2}<5$  and measurement of  $V_{s1}, \theta_1$  and  $V_{s2}, \theta_2$  at this frequency; and

20 determination of the sheet resistance  $R_s$  and junction conductance  $G_s$  using measured SPV signals, its phase shifts,  $V_{s1}, \theta_1$  and  $V_{s2}, \theta_2$  and a set of equations:

$$\frac{V_{S1}}{V_{S2}} = \left| \frac{V_{S1}}{V_{S2}} \right| = \left| \frac{1}{2} k R_0^2 \frac{K_1(kR_0)I_0(kR_0) + K_0(kR_0)I_1(kR_0) - (1/2kR_0)K_1(kR_0)I_1(kR_0)}{I_1(kR_0)[R_1 \cdot K_1(kR_1) - R_2 K_1(kR_2)]} \right| \quad (11)$$

$$\theta_1 - \theta_2 = \operatorname{Arg} \left[ \frac{1}{2} k R_0^2 \frac{K_1(kR_0)I_0(kR_0) + K_0(kR_0)I_1(kR_0) - (1/2kR_0)K_1(kR_0)I_1(kR_0)}{I_1(kR_0)[R_1 \cdot K_1(kR_1) - R_2 K_1(kR_2)]} \right] \quad (12).$$